

Supporting information

Molecular Level Understanding of Adhesion Mechanisms at the Epoxy/Polymer Interfaces

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Materials in Commercial epoxy CE3302

1. Base:

- (1) main component: bisphenol-A-(epichlorhydrin) epoxy resin (50-100 %)
- (2) bis(1,2,2,6,6-pentamethyl-4 piperidiny)sebacate: (2.5-10%)
- (3) 4-nonylphenol: (2.5-10%)

2. Hardener:

- (1) Polyoxypropylenediamine (50-100%)
- (2) 4-nonylphenol (10-25%)

Materials in Commercial epoxy CE3006

1. Base:

- (1) calcium carbonate (25-50%)
- (2) bisphenol-A-(epichlorhydrin) epoxy resin (25-50%)
- (3) oxirane, mono[(C12-14-alkyloxy)methyl] derivs (10-25%)
- (4) 4-nonylphenol (2.5-10%)

2. Hardener :

- (1) Calcium Carbonate (25-50%)
- (2) Polyaminoamide (25-50%)
- (3) Tetraethylenepentamine (2.5-10%)
- (4) Benzyl alcohol (2.5-10%)